

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT6765413

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JAE IN AHN	05/12/2021
KYUNG HWAN KIM	05/12/2021
SUNG HOON YUN	05/12/2021
JANG WON SEO	05/12/2021
KANG SIK MYUNG	05/12/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SKC SOLMICS CO., LTD.
<b>Street Address:</b>	1043, GYEONGGI-DAERO, PYEONGTAEK-SI
<b>City:</b>	GYEONGGI-DO
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	17784
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17349285
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(571)327-5452
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	5713275450
<b>Email:</b>	ipntlaw@ipntlaw.com
<b>Correspondent Name:</b>	IP & T GROUP LLP
<b>Address Line 1:</b>	8230 LEESBURG PIKE
<b>Address Line 2:</b>	SUITE 650
<b>Address Line 4:</b>	VIENNA, VIRGINIA 22182
<b>ATTORNEY DOCKET NUMBER:</b>	PCC104024SKL/US-JS
<b>NAME OF SUBMITTER:</b>	KEON WOO PARK
<b>SIGNATURE:</b>	/Keon Woo PARK/
<b>DATE SIGNED:</b>	06/16/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	

**Total Attachments: 5**

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ASSIGNMENT OF AND DECLARATION FOR APPLICATION  
FOR UNITED STATES LETTERS PATENT

WHEREAS Jae In AHN, hereinafter referred to collectively as the assignor and inventor, has invented a certain improvement relating to POLISHING PAD, PREPARATION METHOD THEREOF AND METHOD FOR PREPARING SEMICONDUCTOR DEVICE USING SAME

☒ said application being attached hereto;  
☐ said application having been filed in the United States Patent and Trademark Office on \_\_\_\_\_, as Application Serial No. \_\_\_\_\_, and was amended on \_\_\_\_\_ (if applicable);  
☐ the specification of which was filed under the Patent Cooperation Treaty on \_\_\_\_\_, Serial No. \_\_\_\_\_, the United States of America being designated.

AND WHEREAS SKC solmics Co., Ltd. of 1043, Gyeonggi-daero, Pyeongtaek-si, Gyeonggi-do 17784, Republic of Korea, hereinafter referred to as the assignee or applicant, is desirous of acquiring the entire right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof;

NOW THIS WITNESSETH, that for and in consideration of One Dollar (\$1.00), and other good and valuable consideration paid by said assignee to said assignor, the receipt of which is hereby acknowledged, said assignor hereby assigns, sells and transfers to said assignee, and said assignee's successors and assigns, the full and exclusive right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof; said assignee, and said assignee's successors and assigns, to have, hold, exercise and enjoy the said application, including any and all divisions and continuations thereof, and the said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges and advantages in anywise arising from or appertaining thereto, for and during the term or terms of any and all such patents when granted, including any and all renewals, reissues and prolongations thereof, for the use and benefit of said assignee, and said assignee's successors and assigns, in as ample and beneficial a manner as the said assignor might or could have held and enjoyed the same, if this assignment had not been made.

AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and said assignee's successors and assigns, in accordance herewith.

As an above-named inventor, I hereby declare that the above-identified application was made or authorized to be made by me, and that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNOR (INVENTOR):

Signature: \_\_\_\_\_

Date: May 12, 2021

Printed or Typed Name: Jae In AHN

ASSIGNMENT OF AND DECLARATION FOR APPLICATION  
FOR UNITED STATES LETTERS PATENT

WHEREAS Kyung Hwan KIM, hereinafter  
referred to collectively as the assignor and inventor, has invented a certain improvement relating to  
POLISHING PAD, PREPARATION METHOD THEREOF AND METHOD FOR PREPARING  
SEMICONDUCTOR DEVICE USING SAME

[X] said application being attached hereto;  
[ ] said application having been filed in the United States Patent and Trademark Office on  
amended on \_\_\_\_\_, as Application Serial No. \_\_\_\_\_, and was  
(if applicable);  
[ ] the specification of which was filed under the Patent Cooperation Treaty on \_\_\_\_\_,  
Serial No. \_\_\_\_\_, the United States of America being designated.

AND WHEREAS SKC solmics Co., Ltd. of 1043, Gyeonggi-daero, Pyeongtaek-si, Gyeonggi-  
do 17784, Republic of Korea  
hereinafter referred to as the assignee or applicant, is desirous of acquiring the entire right, title and interest in  
and to said application, including any and all divisions and continuations thereof, and in and to said invention  
and any and all patents which may be granted therefor, including any and all renewals, reissues and  
prolongations thereof;

NOW THIS WITNESSETH, that for and in consideration of One Dollar (\$1.00), and other good and  
valuable consideration paid by said assignee to said assignor, the receipt of which is hereby acknowledged, said  
assignor hereby assigns, sells and transfers to said assignee, and said assignee's successors and assigns, the full  
and exclusive right, title and interest in and to said application, including any and all divisions and continuations  
thereof, and in and to said invention and any and all patents which may be granted therefor, including any and  
all renewals, reissues and prolongations thereof; said assignee, and said assignee's successors and assigns, to  
have, hold, exercise and enjoy the said application, including any and all divisions and continuations thereof,  
and the said invention and any and all patents which may be granted therefor, including any and all renewals,  
reissues and prolongations thereof, with all the rights, powers, privileges and advantages in anywise arising  
from or appertaining thereto, for and during the term or terms of any and all such patents when granted,  
including any and all renewals, reissues and prolongations thereof, for the use and benefit of said assignee, and  
said assignee's successors and assigns, in as ample and beneficial a manner as the said assignor might or could  
have held and enjoyed the same, if this assignment had not been made.

AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's  
successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any  
and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue  
Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and  
said assignee's successors and assigns, in accordance herewith.

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invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18  
U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNOR (INVENTOR):

Signature: \_\_\_\_\_

Date: May 12, 2021

Printed or Typed Name: Kyung Hwan KIM

**ASSIGNMENT OF AND DECLARATION FOR APPLICATION  
FOR UNITED STATES LETTERS PATENT**

WHEREAS Sung Hoon YUN, hereinafter referred to collectively as the assignor and inventor, has invented a certain improvement relating to POLISHING PAD, PREPARATION METHOD THEREOF AND METHOD FOR PREPARING SEMICONDUCTOR DEVICE USING SAME

☒ said application being attached hereto;  
☐ said application having been filed in the United States Patent and Trademark Office on \_\_\_\_\_, as Application Serial No. \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable);  
☐ the specification of which was filed under the Patent Cooperation Treaty on \_\_\_\_\_, Serial No. \_\_\_\_\_, the United States of America being designated.

AND WHEREAS SKC solmics Co., Ltd. of 1043, Gyeonggi-daero, Pyeongtaek-si, Gyeonggi-do 17784, Republic of Korea hereinafter referred to as the assignee or applicant, is desirous of acquiring the entire right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof;

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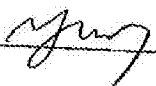
AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and said assignee's successors and assigns, in accordance herewith.

As an above-named inventor, I hereby declare that the above-identified application was made or authorized to be made by me, and that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**ASSIGNOR (INVENTOR):**

Signature:  Date: May 12, 2021  
Printed or Typed Name: Sung Hoon YUN

ASSIGNMENT OF AND DECLARATION FOR APPLICATION  
FOR UNITED STATES LETTERS PATENT

WHEREAS Jang Won SEO, hereinafter  
referred to collectively as the assignor and inventor, has invented a certain improvement relating to  
POLISHING PAD, PREPARATION METHOD THEREOF AND METHOD FOR PREPARING  
SEMICONDUCTOR DEVICE USING SAME

[X] said application being attached hereto;  
[ ] said application having been filed in the United States Patent and Trademark Office on  
\_\_\_\_\_, as Application Serial No. \_\_\_\_\_, and was  
amended on \_\_\_\_\_ (if applicable);  
[ ] the specification of which was filed under the Patent Cooperation Treaty on \_\_\_\_\_,  
Serial No. \_\_\_\_\_, the United States of America being designated.

AND WHEREAS SKC solmics Co., Ltd. of 1043, Gyeonggi-daero, Pyeongtaek-si, Gyeonggi-  
do 17784, Republic of Korea  
hereinafter referred to as the assignee or applicant, is desirous of acquiring the entire right, title and interest in  
and to said application, including any and all divisions and continuations thereof, and in and to said invention  
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I hereby acknowledge that any willful false statement made in this declaration is punishable under 18  
U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNOR (INVENTOR):

Signature: Jang Won SEO Date: May 12, 2021

Printed or Typed Name: Jang Won SEO

ASSIGNMENT OF AND DECLARATION FOR APPLICATION  
FOR UNITED STATES LETTERS PATENT

WHEREAS Kang Sik MYUNG, hereinafter  
referred to collectively as the assignor and inventor, has invented a certain improvement relating to  
POLISHING PAD, PREPARATION METHOD THEREOF AND METHOD FOR PREPARING  
SEMICONDUCTOR DEVICE USING SAME

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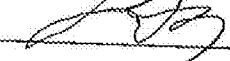
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I hereby acknowledge that any willful false statement made in this declaration is punishable under 18  
U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNOR (INVENTOR):

Signature:  Date: May 12, 2021

Printed or Typed Name: Kang Sik MYUNG